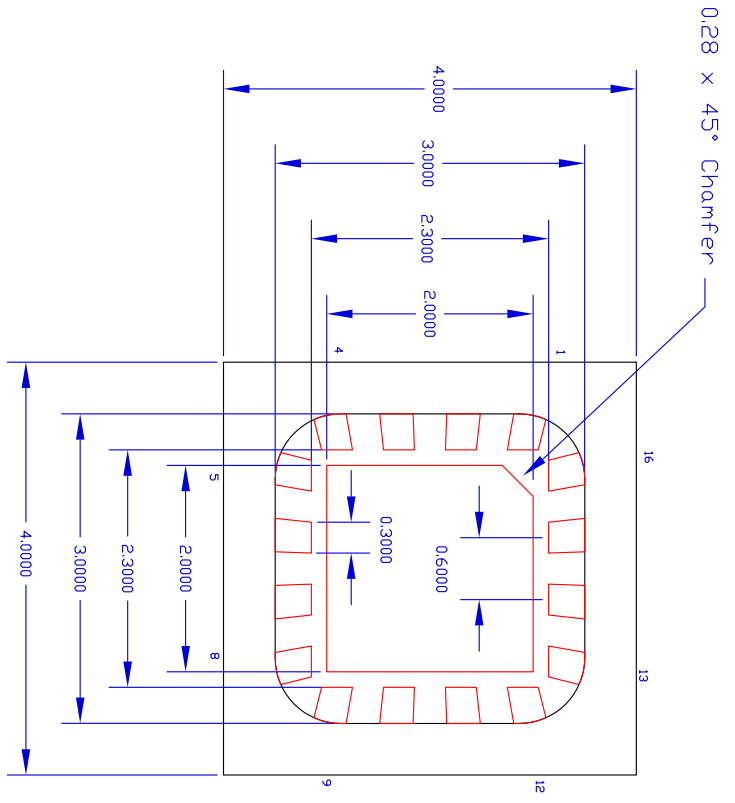
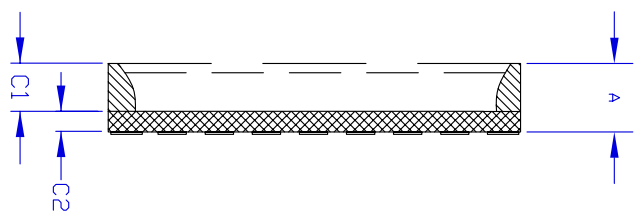


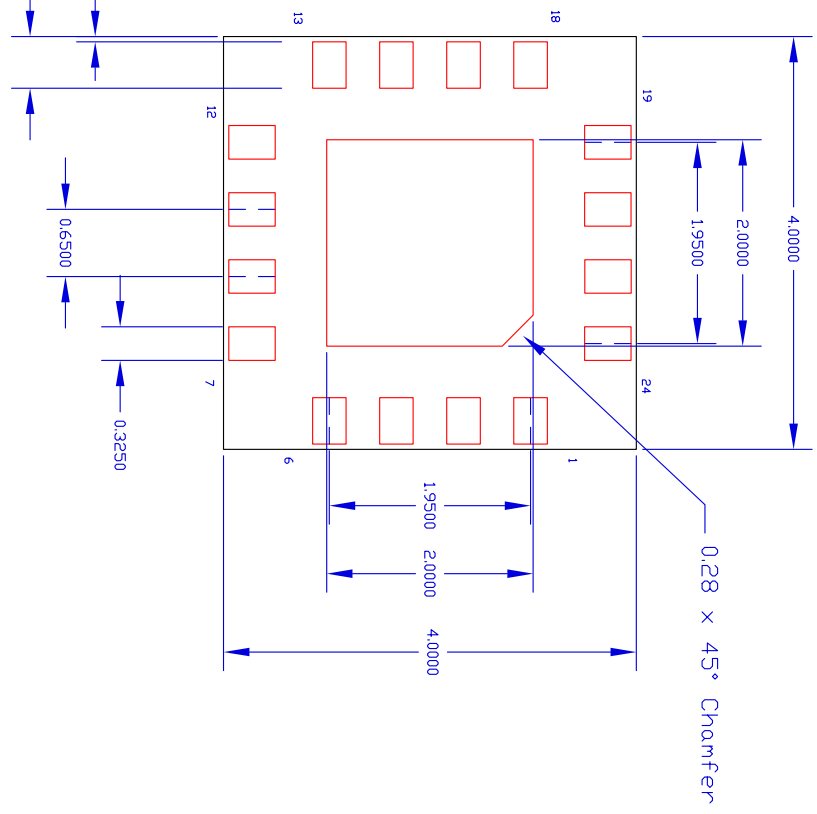
TOP VIEW



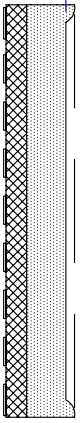
SIDE VIEW



BOTTOM VIEW



Cavity wall
variance
0.05~0.15



SIDE VIEW

HEIGHT TABLE			
SERIES	C1	C2	A
A-QFN	0.63	0.27	0.90
A-TQFN	0.38	0.27	0.65
TOL	+/- 0.10	+/- 0.05	+/- 0.15

OTHER SIZES AVAILABLE

THIS DOCUMENT AND THE TECHNOLOGY IT REPRESENTS ARE, AND SHALL REMAIN, THE PROPRIETARY PROPERTY OF MIRROR SEMICONDUCTOR. THIS DOCUMENT IS PROVIDED TO RECIPIENT ON A CONFIDENTIAL BASIS WITH THE RECIPIENT'S AGREEMENT THAT IT WILL NOT REPRODUCE, COPY, LOAN, EXHIBIT NOR USE, EITHER IN WHOLE OR IN PART, THE DOCUMENT OR ITS CONTENT, EXCEPT IN THE LIMITED WAY AND FOR ITS PRIVATE USE AS PERMITTED BY MIRROR SEMICONDUCTOR.

Note:

1. Organic substrate
2. Cavity Dam: Hysol FP4451TD
3. Pads: Cu/Ni/Au
4. Copper Thickness: 12µm~18µm (0.5~0.7mil)
5. Bonding Pad Gold Thickness: 1.3µm (50 micro-inch)
6. PCB Pads Gold Thickness: 0.13µm (5 micro-inch)
7. Nickel Thickness: 38µm (150 micro-inch)
8. All Dimensions Are mm

TOLERANCES UNLESS NOTED:		APPROVALS		DATE	
X.XX	±	DRAWN TA		11/29/08	
X.XXX	±				
X.XXXX	±				
ALL DIMENSIONS ARE IN:		MFG		TITLE	
<input type="checkbox"/> INCHES <input type="checkbox"/> MILLIMETERS				16-LEAD 4MM P=0.65MM A-QFN (AIR) OPEN CAVITY	
THIRD ANGLE PROJECTION:		SCALE	SIZE	DRAWING NO.	REV
		NONE	A	461610	A
REVISED		DO NOT SCALE DRAWING		SHEET	1 OF 1

